

HVM187WK

Silicon Epitaxial Planar Pin Diode for High Frequency Attenuator

REJ03G0116-0600Z (Previous: ADE-208-056E) Rev.6.00 Oct.08.2003

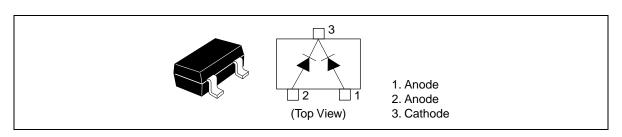
Features

- Low forward resistance. ($r_f = 5.5 \Omega \text{ max}$)
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HVM187WK	H1	MPAK

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	60	V
Forward current	I _F	50	mA
Power dissipation	Pd *1	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

Note: 1. Per one device.

Electrical Characteristics *1

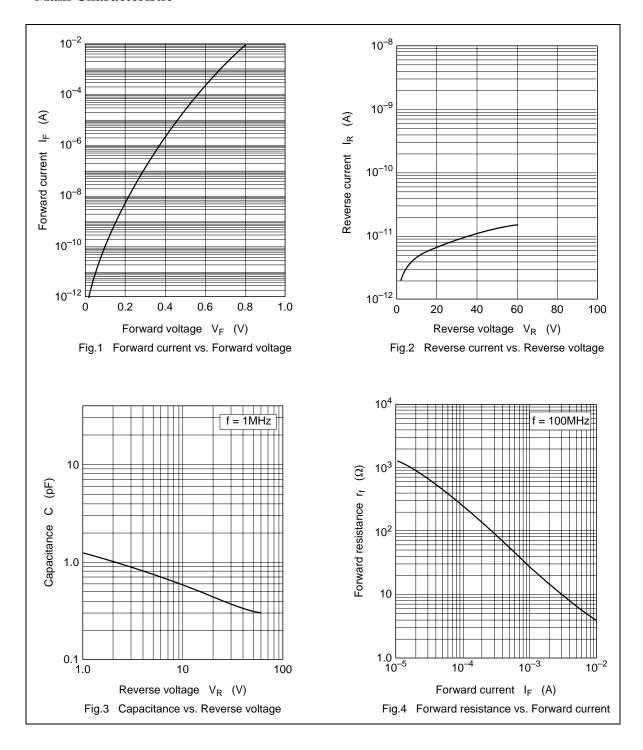
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R	_	_	100	nΑ	V _R = 60 V
Forward voltage	V _F	_	_	1.0	V	I _F = 10 mA
Capacitance	С	_	_	2.4	pF	$V_R = 0 V, f = 1 MHz$
Forward resistance	r _f	3.5	_	5.5	Ω	I _F = 10 mA, f = 100 MHz
ESD-Capability *2	_	200	_	_	V	C = 200 pF, Both forward and reverse direction 1 pulse.

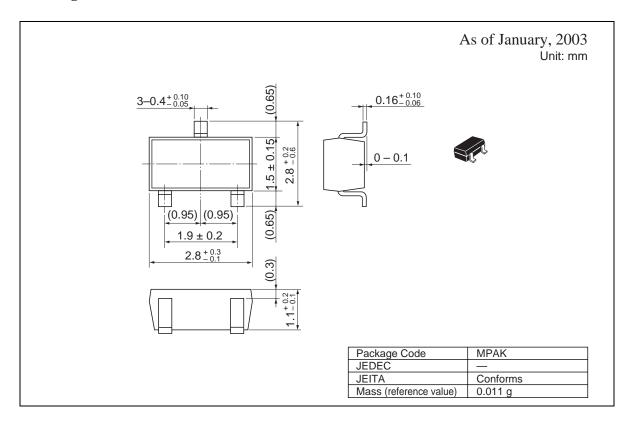
Notes: 1. Per one device.

2. Failure criterion ; $I_R \geq 100 \; nA$ at V_R = 60 V

Main Characteristic



Package Dimensions



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